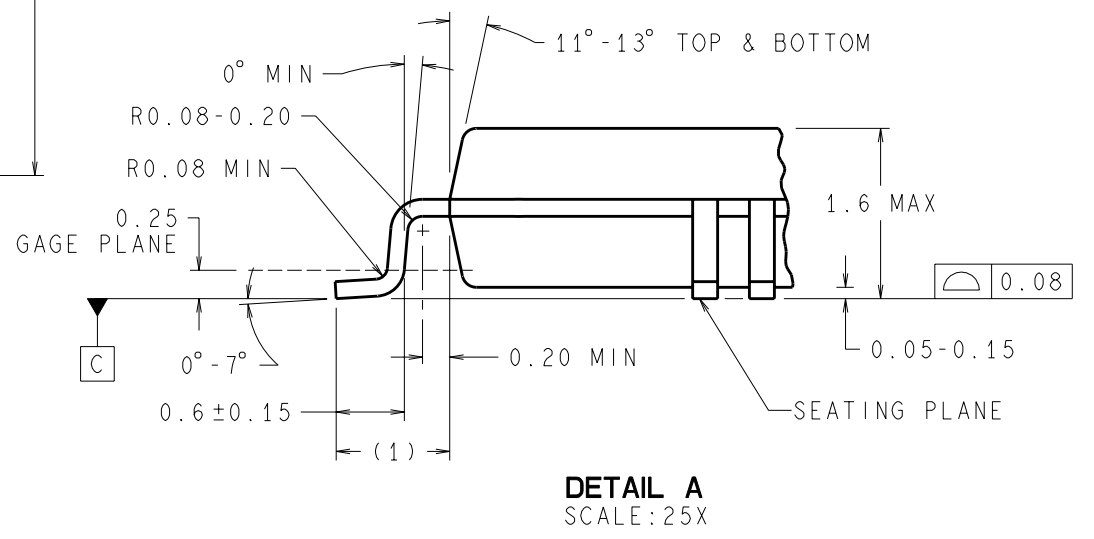


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10711	11/21/1994	DEG/HJK
B	TITLE: LQFP WAS PQFP; UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE	12317	11/10/1999	TL/RW



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC REGISTRATION MS-026, VARIATION BGA,
DATED FEBRUARY 1999.
- 24 X 24 X 1.4mm, 160 LD IS A DEPOPULATED PKG OF
24 X 24 X 1.4mm, 176 LD PER NOTE 3.

APPROVALS	DATE	National Semiconductor		
DRAWN D.E Grady	11/21/1994	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. MARTA SUCHY	11/10/1999	LQFP, JEDEC METRIC, 24 X 24 X 1.4mm, 160 LEAD		
ENGR. CHK. RANDY WALBERG	11/10/1999			
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	(SC)MKT-VPB160A	B
INCH [MM]	FORMERLY: N/A	SHEET 1 of 1		